

N5TL2-U-AS

High Power LED

Introduction

The N5TL2-U-AS product series is a compact, high quality and reliable 4-chip UV LED. Featuring high radiometric power density and design flexibility - the N5 spectrum can be tailored to your application.

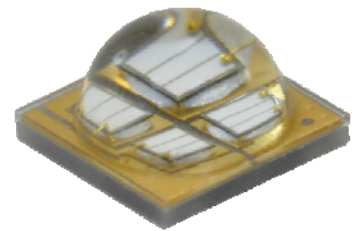


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RoHS Compliant

Characteristics

Absolute Maximum Ratings

Parameter	Rating
	UV Series
DC Forward Current (mA)	700 mA
LED Junction Temperature	150°C
LED Operating Temperature	-40°C~125°C
Storage Temperature	-40°C~125°C
Soldering Temperature	Max. 260°C / Max. 10sec. (JEDEC 020c)
ESD Sensitivity	2,000 V HBM (JESD-22A-114-B)
Preconditioning	Acc. to JEDEC Level 2

Notes:

1. Never operate the LEDs in reverse bias.
2. Do not drive at rated current for more than 5 seconds without proper thermal management.
3. When the LEDs are illuminating, operating current should be decided after considering the packages maximum temperature.
4. Caution: These devices emit high intensity UV/NUV light. Necessary precautions must be taken during operation. Do not look directly into the light or look through the optical system when in operation. Protective eyewear should be worn at all times during operation.
5. Lens discoloration may occur with prolonged exposure to UV/NUV light. Lens material will need to be tested for UV/NUV light compatibility and durability.

General Characteristics at 350mA

Part number	Color	Peak Wavelength, Wp		$2\theta_{1/2}$	Thermal Resistance Junction to Pad
		Min	Max		(°C/W) $R\theta_{J-S}$
N5TL2-U-AS	U40	380	390	135	1.5
	U50	390	400	135	1.5
	U60	400	410	135	1.5
	U70	410	420	135	1.5

Notes:

1. The peak/dominant wavelength is measured with an accuracy of $\pm 1\text{nm}$.

Radiometric Power and Forward Voltage

Part number	Color	Performance at Test Current 350mA				Performance at 700mA
		Group	Minimum Radiation Power (mW)	VF		*Calculated Minimum Radiation Power (mW)
				Min	Max	
N5TL2-U-AS	U40 (380 ~390nm)	GP	800	11	15	1275
		GQ	900	11	15	1350
		HP	1000	11	15	1425
		HQ	1200	11	15	1500
		HR	1400	11	15	2100
	U50 (390~400nm)	HP	1000	11	15	1500
		HQ	1200	11	15	1800
		HR	1400	11	15	2100
		HS	1600	11	15	2400
		I1	1800	11	15	2700
		I2	2000	11	15	3000
		I3	2200	11	15	3300
	U60 (400~410nm)	HP	1000	11	15	1500
		HQ	1200	11	15	1800
		HR	1400	11	15	2100
		HS	1600	11	15	2400
		I1	1800	11	15	2700
		I2	2000	11	15	3000
		I3	2200	11	15	3300
	U70 (410~420nm)	HP	1000	11	15	1500
		HQ	1200	11	15	1800
		HR	1400	11	15	2100
		HS	1600	11	15	2400
		I1	1800	11	15	2700
		I2	2000	11	15	3000
		I3	2200	11	15	3300

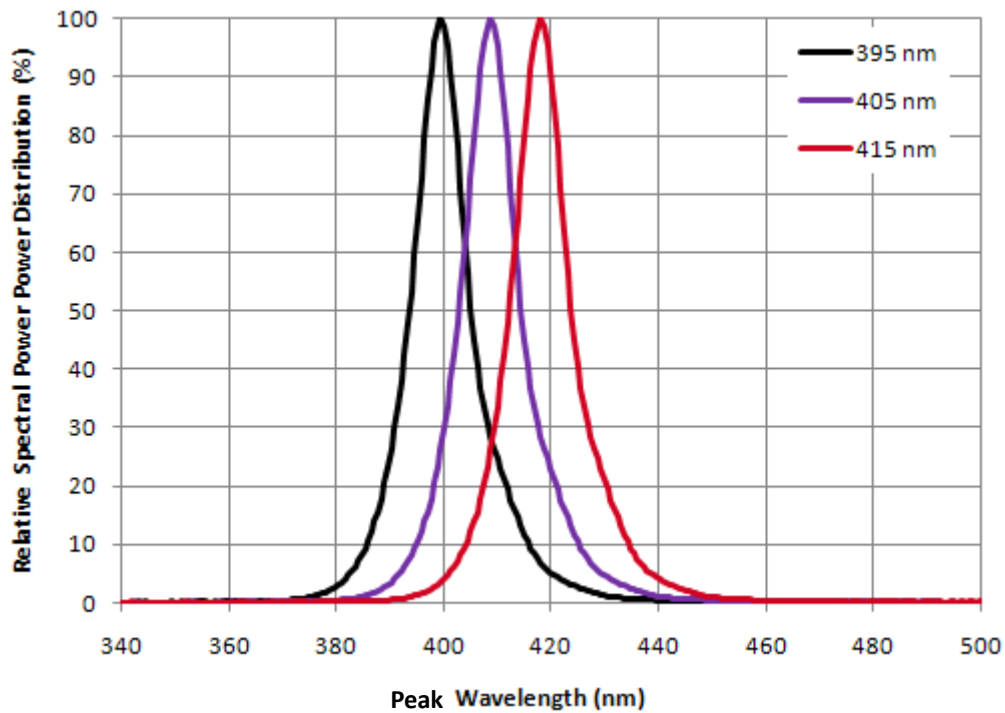
Note:

1. Radiometric power is measured with an accuracy of $\pm 10\%$
2. The forward voltage is measured with an accuracy of $\pm 0.2V$

* Calculated values are for reference only.

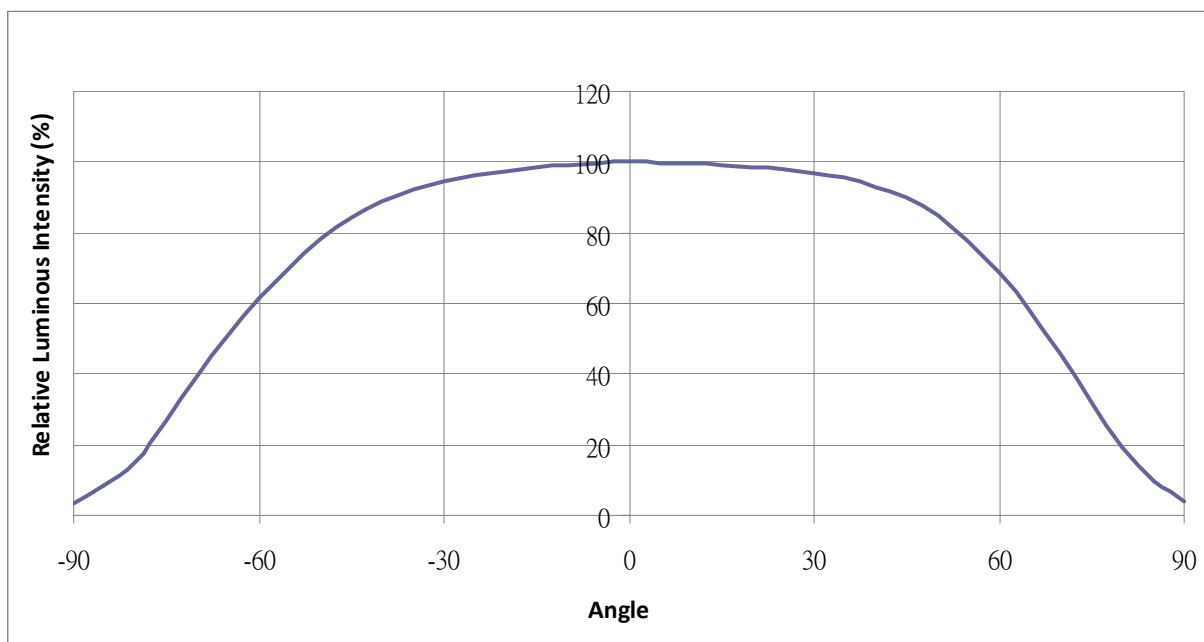
Relative Spectral Power Distribution, $T_j=25\text{ }^{\circ}\text{C}$

UV



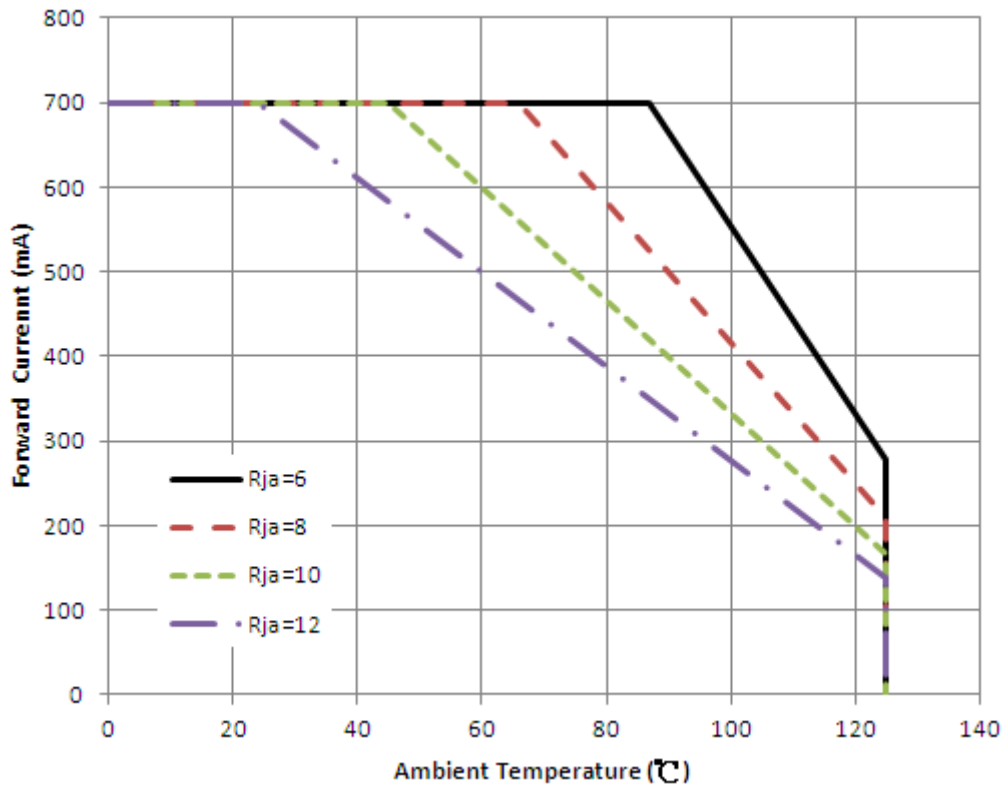
Typical Spatial Radiation Pattern, $T_j=25\text{ }^{\circ}\text{C}$

UV



Thermal Design

Thermal design of the end product is important. The thermal resistance between the junction and the solder point ($R\theta_{JS}$) and the end product should be designed to minimize the thermal resistance from the solder point to ambient in order to optimize the emitter life and optical characteristics. The maximum operation current is determined by the plot of Allowable Forward Current vs. Ambient Temperature.



The junction temperature can be correlated to the thermal resistance between the junction and ambient (Rja) by the following equation.

$$T_j = T_a + R_{ja} \cdot W$$

T_j : LED junction temperature

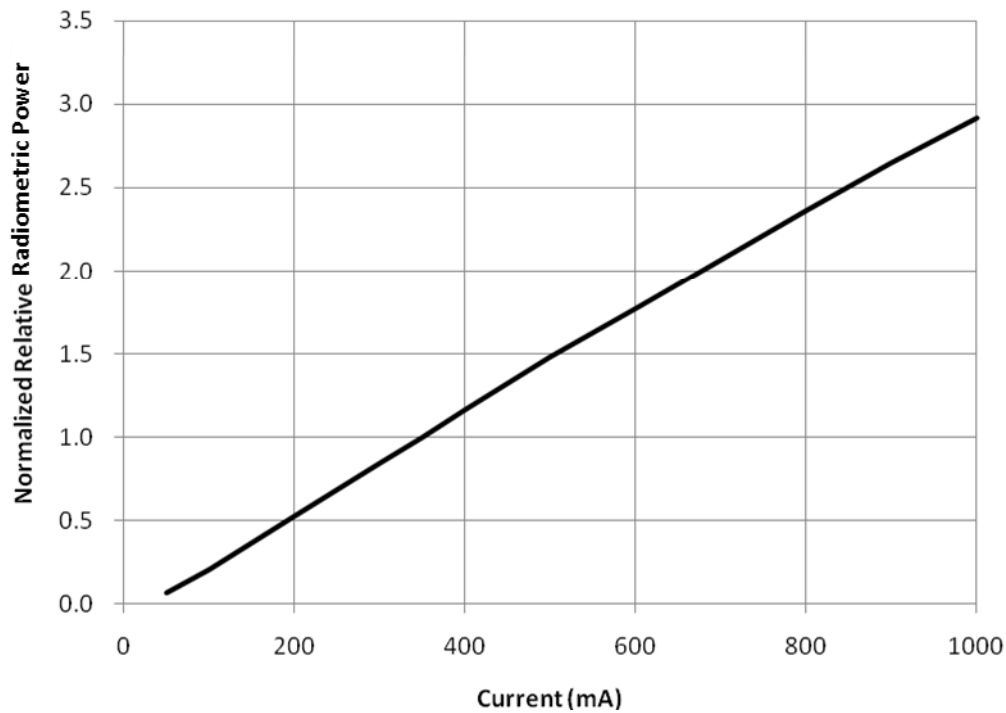
T_a : Ambient temperature

Rja : Thermal resistance between the junction and ambient

W : Input power ($I_F \cdot V_F$)

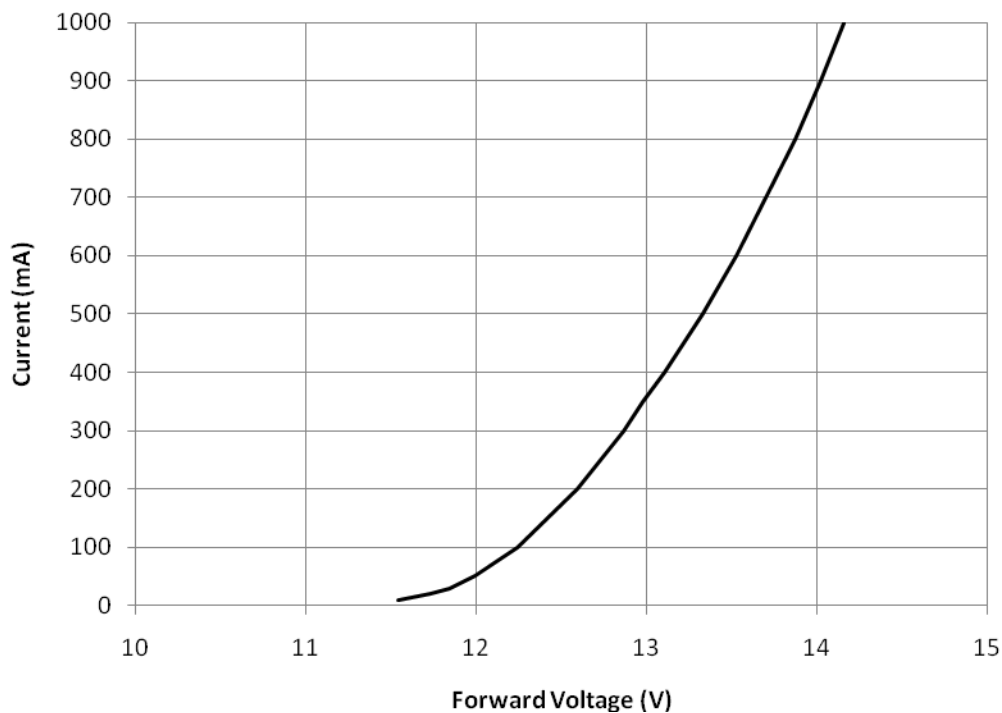
Typical Forward L-I Characteristics, $T_j=25^\circ\text{C}$

UV

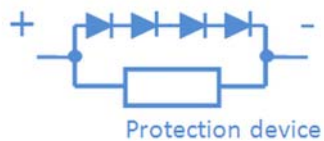
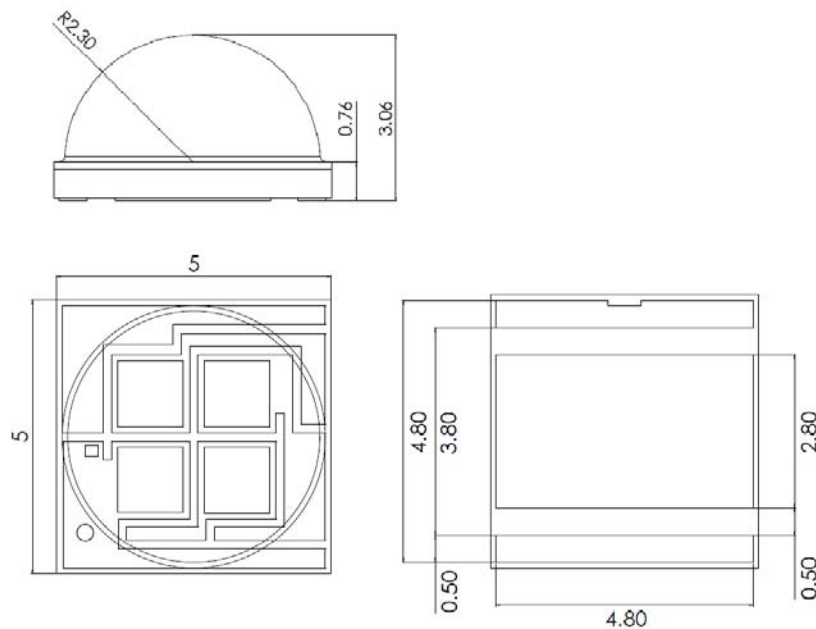
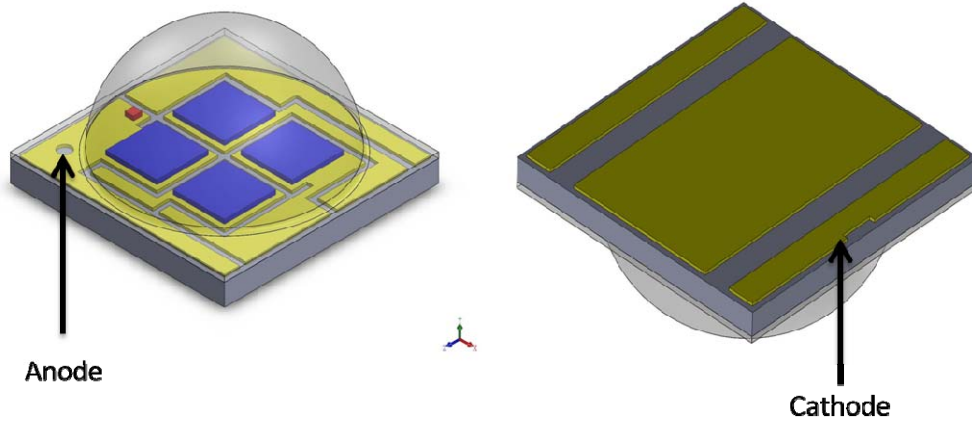


Typical Forward I-V Characteristics, $T_j=25^\circ\text{C}$

UV



Mechanical Dimensions

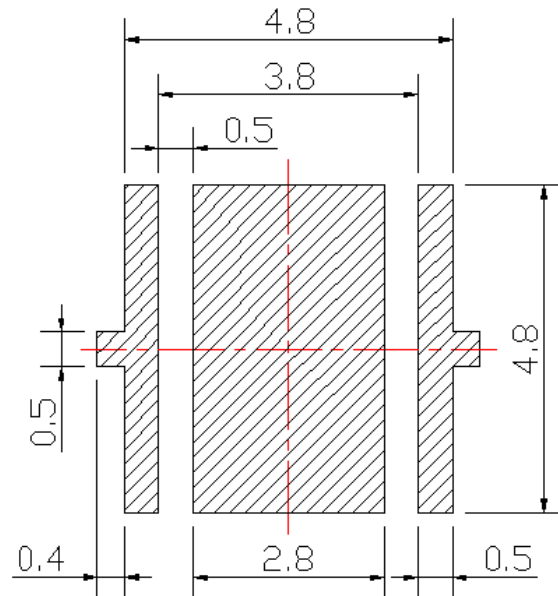


Notes :

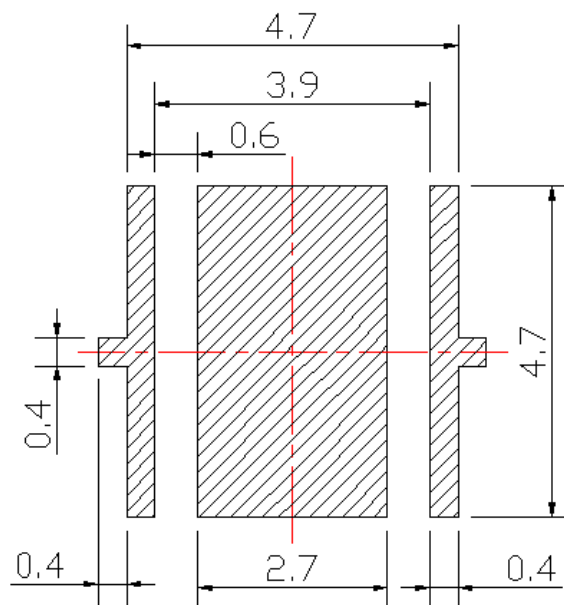
1. Drawing is not to scale
2. All dimensions are in millimeter
3. Dimensions are $\pm 0.13\text{mm}$ unless otherwise indicated

Recommended Solder Pad Design

Recommended Soldering Pad Design



Recommended Stencil Pattern Design (Mark Area is Opening)

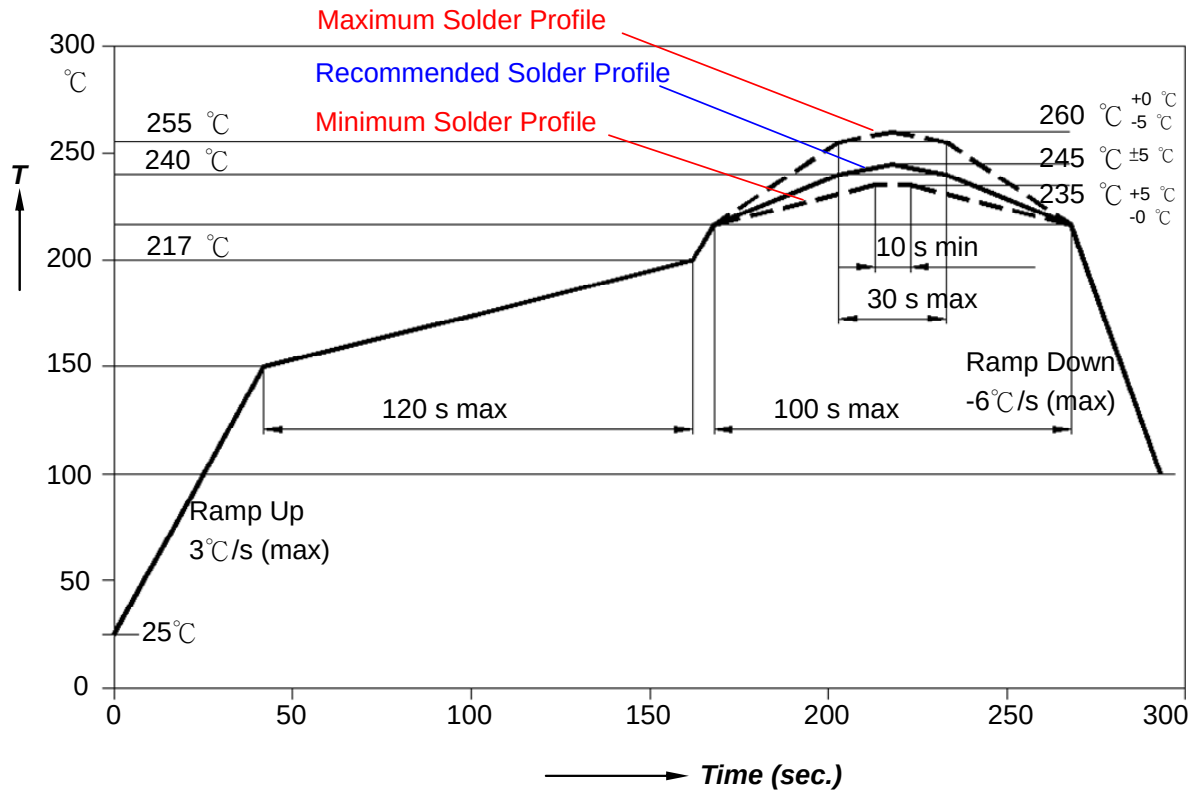


Notes :

1. Drawing is not to scale
2. All dimensions are in millimeter

Recommended Soldering Profile

The LEDs can be soldered using the parameter listed below. As a general guideline, the users are suggested to follow the recommended soldering profile provided by the manufacturer of the solder paste. Although the recommended soldering conditions are specified in the list, reflow soldering at the lowest possible temperature is preferred for the LEDs.



Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Average Ramp-up Rate (T _{smax} to T _p)	3°C/second max.	3°C/second max.
Preheat		
- Temperature Min(T _{smin})	100°C	150°C
- Temperature Max(T _{smax})	150°C	200°C
- Time(t _{smin} to t _{smax})	60-120 seconds	60-180 seconds
Time maintained above:		
- Temperature(T _L)	183°C	217°C
- Time(t _L)	60-150 seconds	60-150 seconds
Peak/classification Temperature(T _p)	215°C	260°C
Time within 5°C of actual Peak Temperature(tp)	10-30 seconds	20-40 seconds
Ramp-Down Rate	6°C/second max.	6°C/second max.
Time 25°C to Peak Temperature	6 minutes max.	8 minutes max.

About Us

SemiLEDs Corporation is a US based manufacturer of ultra-high brightness LED chips with state of the art fabrication facilities in Hsinchu Science Park, Taiwan. SemiLEDs specializes in the development and manufacturing of vertical LED chips in blue (white), green, and UV using a patented copper alloy base. This unique design allows for higher performance and longer lumen maintenance. In December 2008, The World Economic Forum recognized SemiLEDs innovations with the 2009 Technology Pioneer Award. SemiLEDs is fully ISO 9001:2008 and ISO 14001:2004 Certified

SemiLEDs is a publicly traded company on NASDAQ Global Select Market (stock symbol "LEDS"). For investor information, please contact us at investors@semileds.com.

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